

## R/flex JADE® A Series Halogen-Free Adhesive System Flexible Copper Clad Laminate Materials

R/flex JADE® A series flexible circuit materials are the next generation of the industry-leading R/flex CRYSTAL® epoxy adhesive system. Environmentally friendly, these materials are halogen-free, lead-free, and flame retardant. They allow our customers to meet the increasing environmental requirements imposed upon commercial applications worldwide without compromising the performance required in today's demanding flexible circuit designs.

### Product Features & Benefits:

- Green and halogen-free epoxy system
- Superior thermal stability allows R/flex JADE A series material to withstand multiple passes through lead-free soldering
- Excellent dimensional stability and superb peel strength improve process yields and reduce fabrication costs
- Inherent flame retardant performance - passes UL 94 V-0 flame testing
- Transparent adhesive system facilitates optical inspection

### Applications:

R/flex JADE A flexible copper clad laminate Materials is formulated to accommodate the most technically demanding circuit applications: hard disk drives, cellular phones, laptop computers, personal digital assistants, semiconductor packages, and many others.

Typical Values (1)

R/flex JADE® A - Flexible Copper Clad Laminates

Property	Test	Details	Units	Copper Clad Laminates				
				Single Sided	Double Sided	Single Sided	Double Sided	
				A590L8H0	A590L8H8	A590L110	A590L111	
<b>Mechanical Properties</b>								
Peel Strength	IPC-TM-650 method 2.4.9	Method A (as received)	kN/m	1.37	1.29/1.25	1.96	1.80/1.78	
		After Solder Float		1.32	1.25/1.27	1.87	1.82/1.80	
Solder Resistance	IPC-TM-650 method 2.4.13	288°C, 10 sec.		PASS	PASS	PASS	PASS	
Dimensional Stability	IPC-TM-650 method 2.2.4	Method B	MD	%	0.016	-0.012	0.025	0.008
			CMD	%	0.116	0.091	0.050	0.080
		Method C	MD	%	0.006	-0.028	0.015	-0.034
			CMD	%	0.120	0.086	0.043	0.045
<b>Electrical Properties</b>								
Insulation Resistance	IPC-TM-650 method 2.6.3	500V, 60 sec	Ohms	1.65*10 <sup>12</sup>	1.65*10 <sup>12</sup>	1.65*10 <sup>12</sup>	1.65*10 <sup>12</sup>	
Dielectric Constant	IPC-TM-650 method 2.5.5.3	@1MHz	-	3.63	3.63	3.63	3.63	
		@1GHz	-	3.85	3.85	3.85	3.85	
Dissipation Factor	IPC-TM-650 method 2.5.5.3	@1MHz	-	0.02	0.02	0.02	0.02	
Surface Resistance	IPC-TM-650 method 2.5.17	-	Ohms	2.8*10 <sup>15</sup>	2.8*10 <sup>15</sup>	2.8*10 <sup>15</sup>	2.8*10 <sup>15</sup>	
Volume Resistivity		-	Ohms cm	2.1*10 <sup>15</sup>	2.1*10 <sup>15</sup>	2.1*10 <sup>15</sup>	2.1*10 <sup>15</sup>	
Dielectric Strength	ASTM D-149		V/mil	4700	4700	4700	4700	
<b>Physical Properties</b>								
Polyimide Performance	Tensile Modulus	ASTM D-882	@20°C	GPa	4.1	4.1	4.1	4.1
	Tensile Strength			MPa	303	303	303	303
	Elongation			%	90	90	90	90
	CTE	TMA	100 to 200°C	ppm/°C	16	16	16	16
	CHE	HMA	@50°C	ppm%RH	13	13	13	13
	Humidity Absorption	ASTM D-570	D-24/20	%	2.5	2.5	2.5	2.5
Tg	TMA		°C	51	51	51	51	
Chemical Resistance	2N NaOH	immersed peel strength/ (non-immersed peel strength)	*%	PASS	PASS	PASS	PASS	
MEK Resistance	IPC-TM-650 method 2.3.2		%/wt loss	PASS	PASS	PASS	PASS	
Flammability	UL94	File#E122972		VTM-0	VTM-0	VTM-0	VTM-0	

(1) Typical values are a representation of an average value for the population of the property. For specification values contact Rogers Corporation.

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**Environmental Standards:**

R/flex JADE® A series products contain no cadmium, lead, mercury, hexavalent chromium compounds, PBBs, PBDEs and meet or exceed the following industry standards:

- IEC and JPCA halogen-free requirements
- RoHS directives



**Part Number Description:**

Laminate (L) Designations	R/flex A5X0-L-XXX
Copper Type 6=ED, 9=RA	
Side 1 copper thickness in oz./ft <sup>2</sup> 8=0.5 (18µm), 1=(35µm)	
Polyimide film thickness in mils H=0.5 (12.5µm), 1= (25µm)	
Side 2 copper thickness in oz./ft <sup>2</sup> 8=0.5 (18µm), 1=(35µm)	

Laminate Type	Rogers Part Number	Copper Thickness		Polyimide Thickness	
		mil	µm	mil	µm
Single Sided	A590L810	½	18	1	25
Single Sided	A590L110	1	35	1	25
Single Sided	A590L8H0	½	18	½	12
Single Sided	A560LT10	⅓	12	1	25
Single Sided	A560L810	½	18	1	25
Single Sided	A560L110	1	35	1	25
Single Sided	A560LTH0	⅓	12	½	12
Single Sided	A560L8H0	½	18	1	12
Double Sided	A590L818	½	18	1	25
Double Sided	A590L111	1	35	1	25
Double Sided	A590L8H8	½	18	½	12
Double Sided	A560LT1T	⅓	12	1	25
Double Sided	A560L818	½	18	1	25
Double Sided	A560L111	1	35	1	25
Double Sided	A560LTHT	⅓	12	½	12
Double Sided	A560L8H8	½	18	½	12

**Available Configurations:**

Many additional configurations are available as non-standards. Please check with your Rogers representative.

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**Material Construction Information:**

R/flex JADE® A products are constructed with a base dielectric polyimide of Kaneka APICAL® NP film and a standard release sheet of opaque polypropylene encapsulated white paper carrier. Bonding films are manufactured with polypropylene encapsulated paper and a polyester release sheet.

All R/flex® flexible circuit materials are manufactured under rigorous process control where process capabilities are continuously monitored for all critical properties such as peel strength and dimensional stability.

**Storage Conditions:**

Copper clad laminates do not change physical properties during storage and therefore do not have a shelf life. Long exposure to moisture and elevated temperatures may cause copper surface oxidation. Storage in original packaging, located in a dry, cool environment is recommended.

**Applicable Specifications:**

Copper Clad Laminates: IPC 4204/4

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**CONTACT INFORMATION:**

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USA:	Rogers Advanced Circuit Materials, ISO 9002 Certified	Tel: 480-961-1382	Fax: 480-917-5256
Belgium:	Rogers N.V. - Gent	Tel: +32-9-2353611	Fax: +32-9-2353658
Japan:	Rogers Japan Inc.	Tel: 81-3-5200-2700	Fax: 81-3-5200-0571
Taiwan:	Rogers Taiwan Inc.	Tel: 886-2-86609056	Fax: 886-2-86609057
Korea:	Rogers Korea Inc.	Tel: 82-31-716-6112	Fax: 82-31-716-6208
Singapore:	Rogers Technologies Singapore Inc.	Tel: 65-747-3521	Fax: 65-747-7425
China:	Rogers (Shanghai)	Tel: 86-21-63916088	Fax: 86-21-63915060
China:	Rogers (Shenzhen)	Tel: 86-755-8236 6060	Fax: 86-755-8236 6123

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